



2021 CEJC Bill Dull Memorial Scholarship Program

Congratulations,

You have received an application packet for the 2021 CEJC Bill Dull Memorial Scholarship. Enclosed in this packet are procedural guidelines for participating in the scholarship program. The scholarships to be awarded will be a minimum of \$500.

Please submit your completed scholarship package to:

Charleston Engineers Joint Council
Attn: CEJC Scholarship Committee
PO Box 61504
N. Charleston, SC 29419

Or via email to charlestonejc@gmail.com

Submission Deadline: April 23, 2021

Please direct any questions with regards to scholarship requirements or submissions to:

Karl Krull
charlestonejc@gmail.com
864-915-3186

The Charleston Engineers Joint Council is a non-profit organization and operates exclusively for a scientific and educational purpose. Its Mission is to inspire Lowcountry Youth, serve as an advocate of Lowcountry STEM programs, and be the catalyst that creates synergies between our professional member societies, local industry, and educational institutions. The Council encourages joint cooperation of its Member Societies for effective public service, mutual educational programs and assists them in the pursuit of their goals.

CEJC SCHOLARSHIP REQUIREMENTS

Eligibility

Scholarship Applicant's must:

- 1) Be a citizen of the United States
- 2) Be a graduating high school senior of a Lowcountry area high school (Berkeley, Charleston, Dorchester Counties)
- 3) Be able to provide proof of acceptance into an engineering or technology curriculum at an accredited institution for higher learning. (This is NOT limited to 4 year programs of study and does include associate degree programs. e.g., Acceptance into Trident Technical College in one of their technology programs is valid.)
- 4) Have a minimum GPA of 3.0.



Submission Requirements

Eligible participants will be required to:

- 1) Write and submit an essay utilizing one of the following topics;
“Why I want to further my education in technology or engineering?” or
“How I can make a difference through technology or engineering?”
Essays should be no more than two pages in length. They must be typed in 12 point font and double-spaced.
- 2) Submit a package documenting an engineering design or engineering research performed as a result of a pre-engineering (high school) program, or work experience. Packages are to document the design and research process which includes design/research progress (i.e., initial designs and/or test methods as well as their evolution and evaluation), show and detail analytical methods employed, provide an overview of what was learned from the work, and a conclusion indicating how the project went and what, if anything, could be improved upon.
- 3) Copy of student transcript
- 4) Letter of sponsorship from an academic professional that addresses the students STEM related qualification, technical acumen and potential for success in a STEM related field.

Awarding Scholarships

The CEJC Scholarship Committee Scholarship will receipt all scholarship packages by the assigned due date. Those packages received after the submission deadline will not be considered for award. All package submissions will be reviewed and scored by the committee. The scoring rubric is attached for your reference. The applicants with the highest scores will be awarded a minimum of a \$500 scholarship at the discretion of the Scholarship Committee. The winner’s school will be notified and the scholarship will be awarded during the recipient’s annual senior awards night at his or her school pending schedule availability. The recipient is encouraged to use the funds for paying tuition, books or other school fees.

CEJC Bill Dull Memorial Scholarships

This scholarship is in memory of Bill Dull who died in 2011 at the age of 87. Bill was a graduate of the University of Michigan. After serving in the Navy at the end of World War II, he spent his entire career working in various engineering capacities for Detroit Edison, the largest electric utility in the state of Michigan. In 1990 he and his wife Maggie retired to Charleston. He was an active life member of both the American Society of Mechanical Engineers (ASME) for 65 years and the National Society of Professional Engineers (NSPE) for 55 years. Bill was an avid supporter of the Charleston Engineers Joint Council and worked tirelessly to promote the engineering profession.

Release

Please note, if awarded a scholarship the Council will recognize your achievement on our Scholarship web page and other social media.



2021 CEJC/Bill Dull Memorial Scholarship

SCORING RUBRIC

This form is to be completed by the CEJC Review Team only Name of Applicant:

Eligibility: (must satisfy all):

- | | | |
|---|------------------------------|-----------------------------|
| a) United States citizen? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| b) Graduating high school senior? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| c) Completed Application package received on time? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| i. Completed Application Form? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| ii. Proof of acceptance into an engineering or technology curriculum at an accredited institution of higher learning? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| iii. Copy of HS Transcript? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| iv. Essay (2 pages max; double spaced, 12 pt font) included? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| v. Engineering Project submitted? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| vi. Letter of Sponsorship | <input type="checkbox"/> Yes | <input type="checkbox"/> No |
| d) Have a minimum GPA of 3.0? | <input type="checkbox"/> Yes | <input type="checkbox"/> No |

Note: If any of these eligibility criteria is answered "NO" the nomination may be disqualified or points deducted at the discretion of the evaluation committee, but may be appealed if extenuating circumstances exist.

Education/Transcript: (20 pts max):

- | | |
|-------------------------------|---------------------------|
| a) Class Rank (10 pts max) | (Top 50% +3pts) ____ |
| | (Top 25% +5pts) ____ |
| | (Top 10% +7pts) ____ |
| | (Top 5% +10pts) ____ |
| b) GPA 4.0 scale (10 pts max) | (≥3.0 - < 3.2 +3pts) ____ |
| | (≥3.2 - < 3.5 +5pts) ____ |
| | (≥3.5 - < 4.0 +7pts) ____ |
| | (4.0 +10pts) ____ |

Engineering Design/Engineering Research Project: (25 pts max)

- | | |
|--|--------------|
| a) Student demonstrates sound engineering design or use of engineering research practices | (max 5) ____ |
| b) Explains design/research progress (i.e., initial designs and/or test methods as well as their evolution and evaluation) | (max 4) ____ |
| c) Shows and details analytical methods employed | (max 4) ____ |
| d) Provides an overview of what was learned from the work | (max 4) ____ |
| e) Documents a conclusion indicating how project results were derived | (max 4) ____ |
| f) Details what, if anything, could be improved upon in the conclusion | (max 4) ____ |

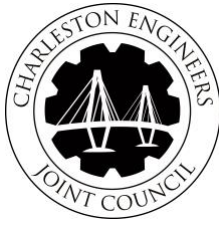
Letter of Sponsorship: (10 pts max)

- | | |
|--|--------------|
| a) Addresses STEM related qualification and technical acumen | (max 5) ____ |
| b) Indicates potential for success in a STEM related field | (max 5) ____ |

Essay: (45 pts max)

- | | |
|--|---------------|
| a) Adequately addresses one of the two topics | (max 5) ____ |
| b) Sufficiently conveys why the applicant wants to further their education or how they can make a difference using technology or engineering | (max 40) ____ |

TOTAL



CEJC/BILL DULL SCHOLARSHIP APPLICATION

Name (Student)

Local Address

City	State	ZIP
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_____ **Telephone Number**

_____ **Email**

**Name, Address and
Phone number of
High School**

Guidance Counselor _____

Grade Point Average _____

Honors/Awards (Academic, tech. society, community participation, attach doc if needed)

Checklist: (items enclosed in submission package)

**Proof of college acceptance
Copy of HS Transcript
Engineering Project**

**Essay
Completed Application
Letter of sponsorship**